

### Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

### SPECIFICATIONS:

ELECTRICAL:

RATED CURRENT: 5A RATED VOLTAGE: 300VDC

WITHSTANDING VOLTAGE:

500VAC (rms) FOR 1 MIN INSULATION RESISTANCE: > 1,000 m $\Omega$  at 500VDC CONTACT RESISTANCE: 13mOhms MAX DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN

OPERATING TEMPERATURE: -55°C TO +105°C

#### MATERIALS:

SHELL: NICKEL PLATED STEEL BRACKET: NICKEL PLATED STEEL

INSULATOR: NYLON 6T, UL 94V-0, BLACK PROCESS TEMP:

**INSULATOR** PATONE #322C, COLOR=Pc99 CONTACT: TIN PLATED PHOSPHOR BRONZE

GOLD FLASH MATING AREA TIN PLATED SOLDER AREA

# ROHS COMPLIANT

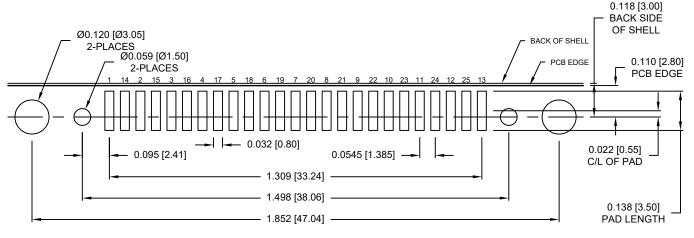
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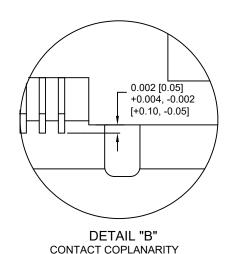
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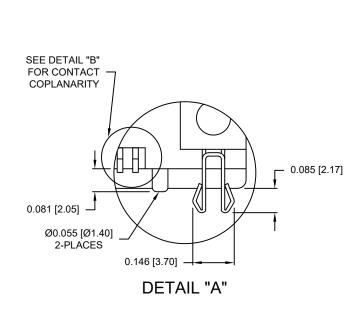
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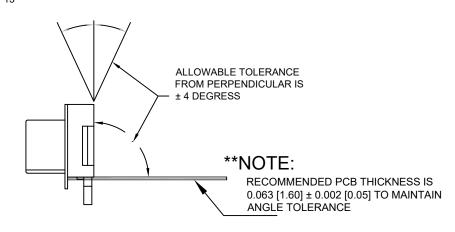




### RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT 1 14 2 15 3 16 4 17 5 18 6 19 7 20 8 21 9 22 10 23 11 24 12 25 13





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